Standard Products

UT54BS3245 8x1 Bus Switch

Preliminary Datasheet February 2015 www.aeroflex.com/busswitch

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FEATURES

- □ Provides cold-sparing capability without the need for actual cold-sparing multiplexer inputs
- □ Bidirectional operation
- \square 3.3V operating lower supply with typical 11Ω switch connection between ports
- $\hfill\Box$ 5V operating lower supply with typical 5 Ω switch connection between ports
- □ Isolates non cold-spared devices from an active bus
- ☐ Ultra low power CMOS technology
- ☐ ESD rating HBM: 2000V, Class 2
- ☐ Operational environment:
 - Total dose: 300 krad(Si)
 - Latchup immune (LET <= 100 MeV-cm2/mg)
- □ Packaging:
 - 20-lead flatpack
- ☐ Standard Microelectronics Drawing (SMD)
 - QML Q and V pending

INTRODUCTION

The UT54BS3245 provides eight channels of high-speed CMOS compatible bus switching. The package is to provide a standard '245 device pin out. The low on-state resistance of the switch allows connections to be made with minimal propagation delay. The device is organized as one 8-channel switch. When the output-enable (/EN) input is low, the switch is on, and port A is connected to port B. When /EN is high, the switch is open, and the high-impedance state exists between the two ports.

APPLICATIONS INFORMATION

Memory Interface

Solution for multiple memory devices on a bus – isolates heavy loading

Bus Isolation

- Ability to electrically isolate a device, or banks of devices, from memory bus or ADC output when not needed
- Enables bank switching for redundancy or device failure
- Provides cold-sparing capability without the need for actual cold-sparing buffers

Redundancy

 Allows multiple non cold-spare devices to be present on a bus

Supports Analog Applications

- In voltage range: 3.0 to 3.6V or 4.5 to 5.5V
 - Signal isolation: -60dB
- Bandwidth (3dB): 500 MHz

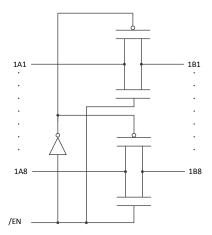


Figure 1. UT54BS3245 Block Diagram

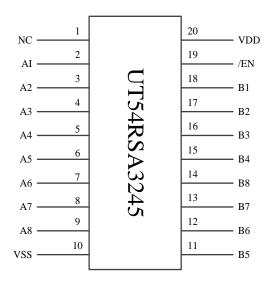


Figure 2. UT54BS3245 Pinout

PIN DESCRIPTION

Pin No.	Name	Description
2, 3, 4, 5, 6, 7, 8, 9	nAn	Port A pins
11, 12, 13, 14, 15, 16,	nBn	Port B pins
17, 18		
19	/EN	Active LOW enable pin
10	V_{SS}	Ground Pin
20	V_{DD}	Supply Pin, +3.3V –or- +5.0V
1	NC	No Connect
		(electrically not connected to die)

TRUTH TABLE

INPUT (/EN) Function		
L	A port to B port	
	-or-	
	B port to A port	
Н	DISCONNECT	

ABSOLUTE MAXIMUM RATINGS 1

Symbol	Parameter		MAX	Unit
V_{DD}^2	Positive Output Supply Voltage	-0.5	7.2	V
V_I^2	Voltage on an Input pin during operation		V_{DD}^{+} 0.3V	V
I_{CCC}	Continuous DC Channel Current		65	mA
P_D^{-3}	Maximum package power dissipation permitted at T_C =125°C		1.6	W
$T_{\rm J}$	Junction Temperature		+150	°C
$\Theta_{ m JC}$	Thermal resistance, junction-to-case		15	°C/W
T_{STG}	Storage Temperature	-65	+150	°C
ESD	ESD protection (Human Body Model) Class 2		2000	V

Notes:

- 1. Permanent device damage may occur if absolute maximum ratings are exceeded. Functional operation should be restricted to recommended operating conditions. Exposure to absolute maximum rating conditions for extended periods may affect device reliability and performance.
- 2. All voltages referenced to VSS
- 3. Per MIL-STD-883, method 1012.1, section 3.4.1, PD=(Tj(max) Tc(max)) / Ojc

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	LIMIT	Unit
V _{DD} ¹	Positive Output Supply Voltage	3.0 to 3.6 or 4.5 to 5.5	V
V _{IN} ¹	Input Voltage on any pin	0.0 to V_{DD}	V
T _C	Case Temperature Range	-55 to +125	°C
t_R	Rise time	>5	ns
t_{F}	Fall time	>5	ns
I_{CCC}	Continuous DC Channel Current	60	mA

Notes:

1. All voltages referenced to VSS

OPERATIONAL ENVIROMENT

PARAMETER	LIMIT	UNITS
Total Ionizing Dose (TID)	3.0E5	rad(Si)
Single Event Latchup (SEL)	>100	MeV-cm ² /mg

DC CHARACTERISTICS*,1

(V_{DD}= $5.0V \pm 0.5V$, $3.3V \pm 0.3V$, $-55^{\circ}C < T_C < +125^{\circ}C$); Unless otherwise noted, Tc is per the temperature range ordered

Symbol	Parameter	Condition		MIN	MAX	Unit
V _{IH}	High level input voltage	V _{DD} =3.6V, 5.5V		0.7*V _{DD}		V
V _{IL}	Low level input voltage	V _{DD} =3.0V, 4.5V			0.3*V _{DD}	V
I_{ID}	Leakage current digital	$V_{DD} = MAX;$ $V_{I} = V_{DD} \text{ or } V_{SS}$		-1	1	μΑ
I_{IA}	Leakage current analog	$V_{DD} = MAX;$ $V_{I} = V_{DD} \text{ or } V_{SS}$		-3	3	μΑ
I_{DD}	Active Supply Current	$V_{DD} = 3.6V, 5.5V$			0.5	mA/MHz
I_{DDQ}	Quiescent Supply Current	$V_{DD} = MAX;$ $I_{O} = 0mA;$ $V_{I} = V_{DD} \text{ or } V_{SS}$			15	μΑ
C _I	Input Capacitance (/EN)	$V_{\rm I} = V_{\rm DD}$ or VSS	S		5	pF
C _{IO(OFF)}	I/O Capacitance when device OFF	$\begin{aligned} &V_{DD} = MAX \\ &V_{O} = V_{DD} \text{ or VSS} \\ &V_{I} = V_{DD}/2 \\ &/EN = V_{DD} \end{aligned}$			5	pF
C _{IO(ON)}	I/O Capacitance when device ON	$V_{DD} = MAX$ $V_{O} = open$ $V_{I} = V_{DD}/2$ $/EN = 0V$			16	pF
R _{ONL} ^{2,3}	Resistance through switch	$V_{DD} = 4.5V$ $V_{I} = VSS$	$I_{O} = 30\text{mA}$ $I_{O} = 15\text{mA}$		10 13	Ω
		$V_{DD} = 3.0V$ $V_{I} = VSS$	$I_{O} = 30\text{mA}$ $I_{O} = 15\text{mA}$		10 13	Ω
R _{ONM} ^{2,3}	Resistance through switch	$V_{DD}=4.5V$ $V_{I}=V_{DD}/2$	$I_{O} = -30 \text{mA}$ $I_{O} = -15 \text{mA}$		10 13	Ω
		$V_{DD}=3.0V$ $V_{I}=V_{DD}/2$	$I_{O} = -30 \text{mA}$ $I_{O} = -15 \text{mA}$		10 13	Ω
R _{ONH} 1,2	Resistance through switch	$V_{DD}=4.5V$ $V_{I}=V_{DD}$	$I_{O} = -30 \text{mA}$ $I_{O} = -15 \text{mA}$		10 13	Ω
		$V_{DD} = 3.0V$ $V_{I} = V_{DD}$	$I_{O} = -30 \text{mA}$ $I_{O} = -15 \text{mA}$		10 13	Ω

Symbol	Parameter	Condition		MIN	MAX	Unit
R _{ON(Flat)}	Switch On Resistance	$V_{DD} = 3.0 V, 4.5 V$ $V_{I} = V_{DD}$	$I_{O} = -30\text{mA}$ $I_{O} = -15\text{mA}$		5 6	Ω

Notes:

- * For devices procured with a total ionizing dose tolerance guarantee, the post-irradiation performance is guaranteed at 25°C per MIL-STD-883 Method 1019, Condition A up to the maximum TID level procured.
- 1. Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.
- 2. Guaranteed by design.

AC CHARACTERISTICS *,1

(V_{DD}= $5.0V \pm 0.5V$, - $55^{\circ}C < T_C < +125^{\circ}C$); Unless otherwise noted, T_C is per the temperature range ordered

Symbol	From (INPUT)	To (OUTPUT)	Cond.	MIN	MAX	Unit
t_{PD30}^{1}	A or B	B or A	$I_{I} = +/-30mA$		500	ps
t _{PD15} 1	A or B	B or A	$I_I = +/-15mA$		650	ps
$t_{\rm EN}$	/EN=V _{SS}	A or B		1	5	ns
$t_{ m DIS}$	$/EN=V_{DD}$	A or B		1	7	ns

(V_{DD} = 3.3V ±0.3V, -55°C < T_C < +125°C); Unless otherwise noted, T_C is per the temperature range ordered

Symbol	From (INPUT)	To (OUTPUT)	Cond.	MIN	MAX	Unit
t_{PD30}^{1}	A or B	B or A	$I_{I} = +/-30mA$		1	ns
$t_{\rm PD15}^{-1}$	A or B	B or A	$I_I = +/-15mA$		1.3	ns
t_{EN}	$/EN=V_{SS}$	A or B		1	7	ns
$t_{ m DIS}$	$/EN=V_{DD}$	A or B		1	8	ns

Notes:

^{*} For devices procured with a total ionizing dose tolerance guarantee, the post-irradiation performance is guaranteed at 25°C per MIL-STD-883 Method 1019, Condition A up to the maximum TID level procured.

1.	The propagation delay through the channel is based upon the RC time constant of the channel
	resistance and switch ON capacitance, 11 Ω and 17pF.

Symbol	Parameter	Condition	MIN	MAX	Unit
X _{TALK} ¹	Cross talk between channels $V_{DD} = 5.0V$	$RL = 50\Omega, CL = 50pF,$ $f = 1MHz,$ $V_{IN1} = 1V_{RMS}$ Centered at $V_{DD}/2$		-60	dB
X _{TALK} ¹	Cross talk between channels $V_{DD} = 3.3V$	$RL = 50\Omega, CL = 50pF,$ $f = 1MHz,$ $V_{IN1} = 1V_{RMS}$ Centered at $V_{DD}/2$		-60	dB
I _{SOOFF} ¹	Off Isolation	$RL = 50\Omega, CL = 50pF,$ $f = 1MHz,$ $V_{IN1} = 1V_{RMS}$ Centered at $V_{DD}/2$		-60	dB

Notes:

1. Guaranteed by design.

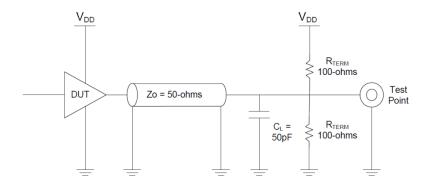


Figure 3. Output Test Load Circuit

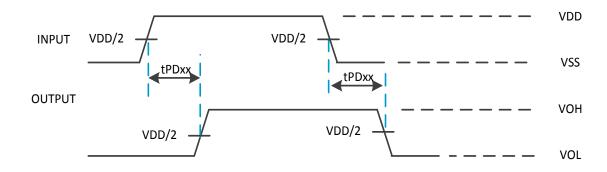


Figure 4. Propagation Waveform

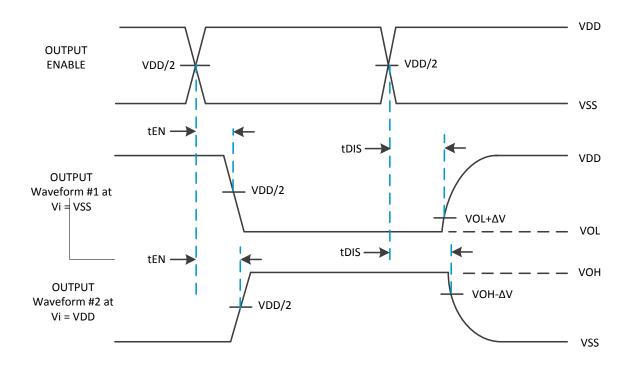
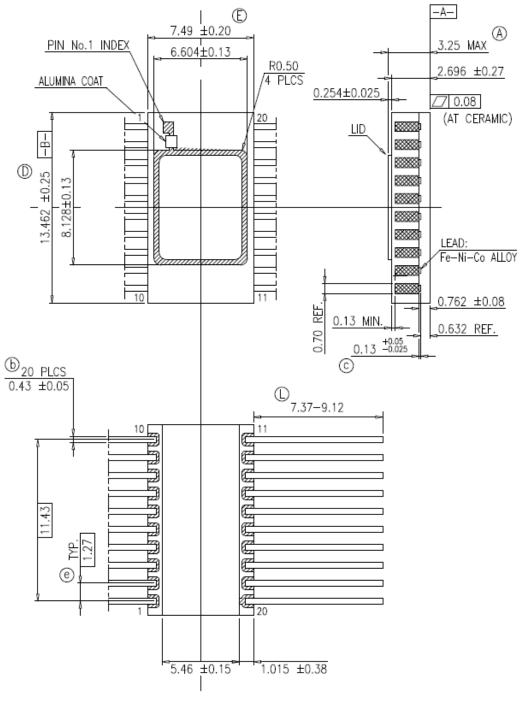


Figure 5. Propagation Waveform

PACKAGING



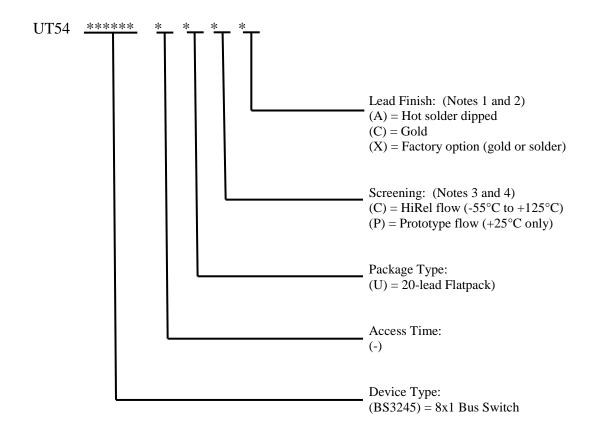
NOTES:

- 1. THE LID IS CONNECTED TO VSS.
- 2. DIMENSIONS ARE IN MILLIMETERS.

Figure 6. 20-lead Ceramic Flatpack

ORDERING INFORMATION

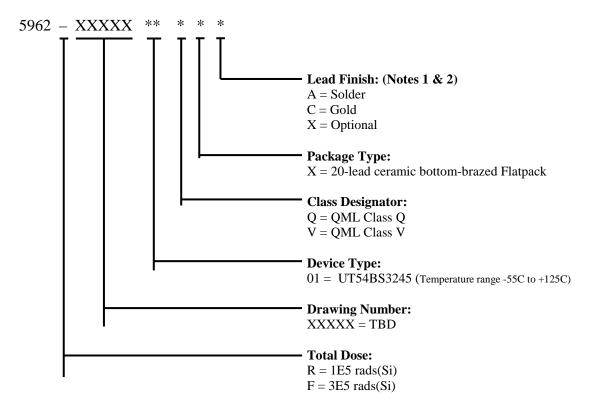
UT54BS3245 8x1 Bus Switch Analog:



Notes:

- 1. Lead finish (A,C, or X) must be specified.
- 2. If an "X" is specified when ordering, then the part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
- 3. Prototype flow per Aeroflex Manufacturing Flows Document. Tested at 25°C only. Lead finish is GOLD ONLY. Radiation neither tested nor guaranteed.
- 4. HiRel Temperature Range flow per Aeroflex Manufacturing Flows Document. Devices are tested at -55°C, room temp, and +125°C. Radiation neither tested nor guaranteed.

UT54BS3245 Bus Switch Analog SMD:



Notes:

- 1. Lead finish (A,C, or X) must be specified.
- 2. If an "X" is specified when ordering, part marking will match the lead finish and will be either "A" (solder) or "C" (gold).

Aeroflex Colorado Springs - Datasheet Definition

Advanced Datasheet - Product In Development

Preliminary Datasheet - Shipping Prototype

Datasheet - Shipping QML & Reduced Hi - Rel

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